5.0 V, 750 mA Low Dropout Linear Regulator with Lower RESET Threshold

The CS8129 is a precision 5.0 V linear regulator capable of sourcing 750 mA. The $\overline{\text{RESET}}$ threshold voltage has been lowered to 4.2 V so that the regulator can be used with 4.0 V microprocessors. The lower $\overline{\text{RESET}}$ threshold also permits operation under low battery conditions (5.5 V plus a diode). The $\overline{\text{RESET}}$'s delay time is externally programmed using a discrete RC network. During power up, or when the output goes out of regulation, $\overline{\text{RESET}}$ remains in the low state for the duration of the delay. This function is independent of the input voltage and will function correctly as long as the output voltage remains at or above 1.0 V. Hysteresis is included in the Delay and the $\overline{\text{RESET}}$ comparators to improve noise immunity. A latching discharge circuit is used to discharge the delay capacitor when it is triggered by a brief fault condition.

The regulator is protected against a variety of fault conditions: i.e. reverse battery, overvoltage, short circuit and thermal runaway conditions. The regulator is protected against voltage transients ranging from –50 V to +40 V. Short circuit current is limited to 1.2 A (typ).

The CS8129 is packaged in a 5 lead TO-220 and a 16 lead surface mount package.

Features

- 5.0 V ±3.0% Regulated Output
- Low Dropout Voltage (0.6 V @ 0.5 A)
- 750 mA Output Current Capability
- Reduced RESET Threshold for use with 4.0 V Microprocessors
- Externally Programmed RESET Delay
- Fault Protection
 - Reverse Battery
 - 60 V, -50 V Peak Transient Voltage
 - Short Circuit
 - Thermal Shutdown



ON Semiconductor™

http://onsemi.com



TO-220 FIVE LEAD T SUFFIX CASE 314D



TO-220 FIVE LEAD TVA SUFFIX CASE 314K



TO-220 FIVE LEAD THA SUFFIX CASE 314A



SO-16L DW SUFFIX CASE 751G

ORDERING INFORMATION

Device	Package	Shipping
CS8129YT5	TO-220* STRAIGHT	50 Units/Rail
CS8129YTHA5	TO-220* VERTICAL	50 Units/Rail
CS8129YTVA5	TO-220* HORIZONTAL	50 Units/Rail
CS8129YDW16	SO-16L	46 Units/Rail
CS8129YDWR16	SO-16L	1000 Tape & Reel

^{*}Five lead.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 8 of this data sheet.

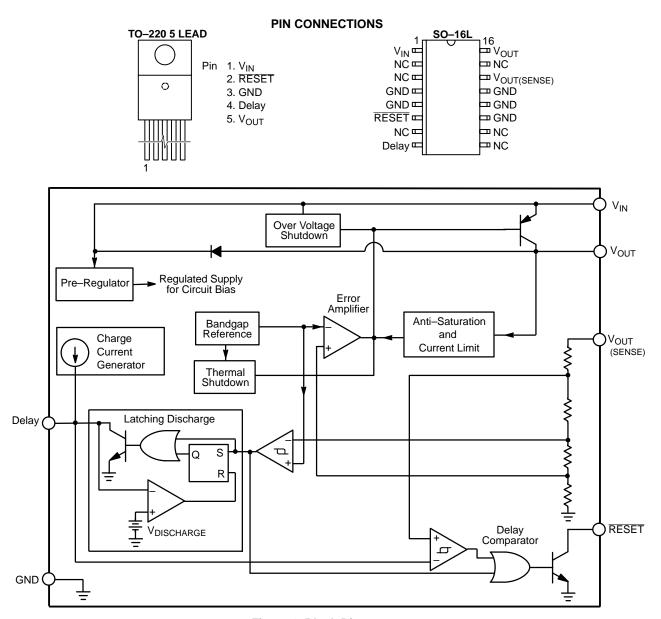


Figure 1. Block Diagram

ABSOLUTE MAXIMUM RATINGS*

Rating			Unit
Input Operating Range		-0.5 to 26	V
Power Dissipation		Internally Limited	-
Peak Transient Voltage (46 V Load Dump @ 14 V V _{IN})			V
Output Current			-
Electrostatic Discharge (Human Body Model)			kV
Junction Temperature		-55 to +150	°C
Storage Temperature Range		-55 to +150	°C
Lead Temperature Soldering:	Wave Solder (through hole styles only) (Note 1.) Reflow (SMD styles only) (Note 2.)	260 peak 230 peak	°C

 ^{1. 10} second maximum.

^{2. 60} seconds max above 183°C.

^{*}The maximum package power dissipation must be observed.

CS8129

Characteristic	Test Conditions	Min	Тур	Max	Unit
Output Stage (V _{OUT)}					•
Output Voltage	ut Voltage -		5.0	5.15	V
Dropout Voltage	I _{OUT} = 500 mA	-	0.35	0.60	V
Supply Current	I _{OUT} = 10 mA I _{OUT} = 100 mA I _{OUT} = 500 mA	- - -	2.0 6.0 55	7.0 12 100	mA mA mA
Line Regulation	$6.0 \text{ V} \le \text{V}_{\text{IN}} \le 26 \text{ V}, \text{I}_{\text{OUT}} = 50 \text{ mA}$	-	5.0	50	mV
Load Regulation	50 mA ≤ I _{OUT} ≤ 500 mA, V _{IN} = 14 V	_	10	50	mV
Ripple Rejection	f = 120 Hz, V _{IN} = 7.0 to 17 V, I _{OUT} = 250 mA	54	75	_	dB
Current Limit	-	0.75	1.20	_	А
Overvoltage Shutdown	-	32	_	40	V
Reverse Polarity Input Voltage DC	V _{OUT} ≥ −0.6 V, 10 Ω Load	-15	-30	_	V
Thermal Shutdown	Guaranteed by Design	150	180	210	°C
RESET and Delay Functions					
Delay Charge Current	V _{DELAY} = 2.0 V	5.0	10	15	μА
RESET Threshold	V_{OUT} Increasing, $V_{RT(ON)}$ V_{OUT} Decreasing, $V_{RT(OFF)}$	4.05 4.00	4.35 4.20	4.50 4.45	V
RESET Hysteresis	$V_{RH} = V_{RT(ON)} - V_{RT(OFF)}$	50	150	250	mV
Delay Threshold	Charge, V _{DC(HI)} Discharge, V _{DC(LO)}	3.25 2.85	3.50 3.10	3.75 3.35	V V
Delay Hysteresis	_	200	400	800	mV
RESET Output Voltage Low	1.0 V < V_{OUT} < $V_{RT(L)}$, 3.0 kΩ to V_{OUT}	_	0.1	0.4	V
RESET Output Leakage	V _{OUT} > V _{RT(H)} Current	_	0	10	μА
Delay Capacitor Discharge Voltage	Discharge Latched "ON", V _{OUT} > V _{RT}	-	0.2	0.5	V
Delay Time	C _{DELAY} = 0.1 μF, Note 4.	16	32	48	ms

^{3.} To observe safe operating junction temperatures, low duty cycle pulse testing is used in tests where applicable.

$$\mbox{DelayTime} = \frac{\mbox{C}_{\mbox{Delay}} \times \mbox{V}_{\mbox{Delay}} \mbox{Threshold Charge}}{\mbox{ICharge}} = \mbox{C}_{\mbox{Delay}} \times 3.5 \times 10^5 \mbox{(typ)}$$

^{4.} Assuming ideal capacitor.

PACKAGE LEAD DESCRIPTION

PACKAG	PACKAGE LEAD #		
SO-16L	TO-220 5 LEAD	LEAD SYMBOL	FUNCTION
1	1	V _{IN}	Unregulated supply voltage to IC.
16	5	V _{OUT}	Regulated 5.0 V output.
4, 5, 11, 12, 13	3	GND	Ground Connection.
8	4	Delay	Timing capacitor for RESET function.
6	2	RESET	CMOS/TTL compatible output lead. RESET goes low whenever V _{OUT} drops below 6.0% of it's regulated value.
14	N/A	V _{OUT(SENSE)}	Remote sensing of output voltage.

TYPICAL PERFORMANCE CHARACTERISTICS

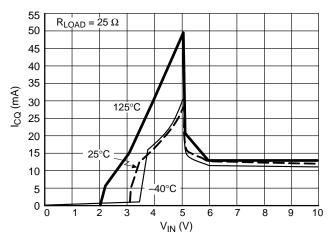


Figure 2. Quiescent Current vs. Input Voltage Over Temperature

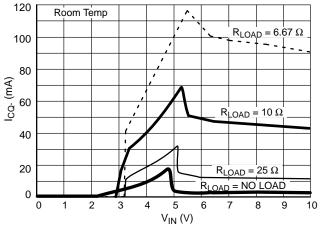


Figure 3. Quiescent Current vs. Input Voltage Over Load Resistance

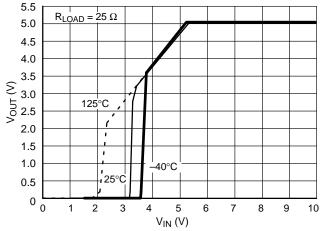


Figure 4. Output Voltage vs. Input Voltage Over Temperature

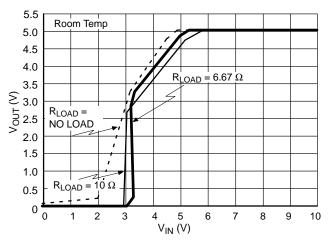


Figure 5. V_{OUT} vs. V_{IN} Over R_{LOAD}

TYPICAL PERFORMANCE CHARACTERISTICS

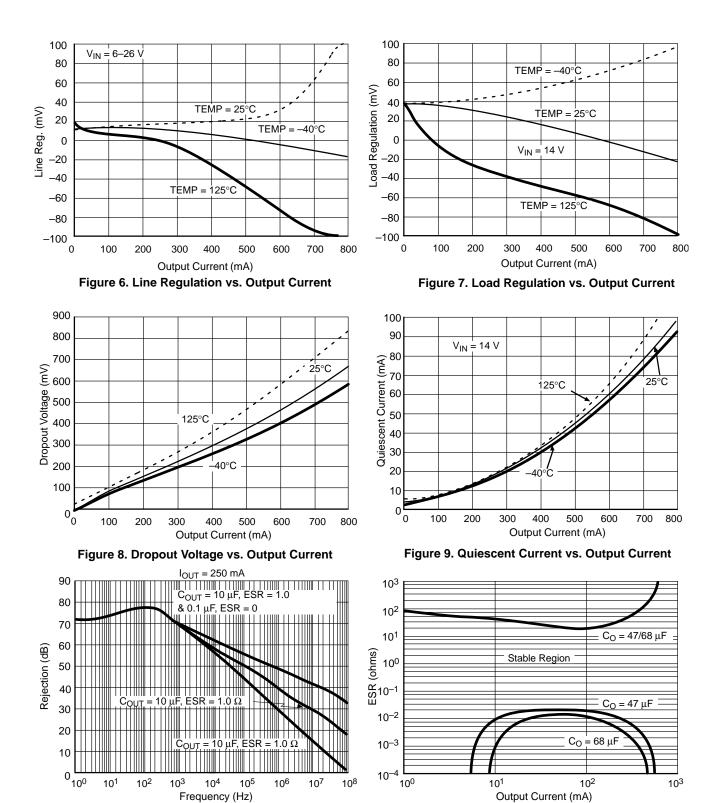
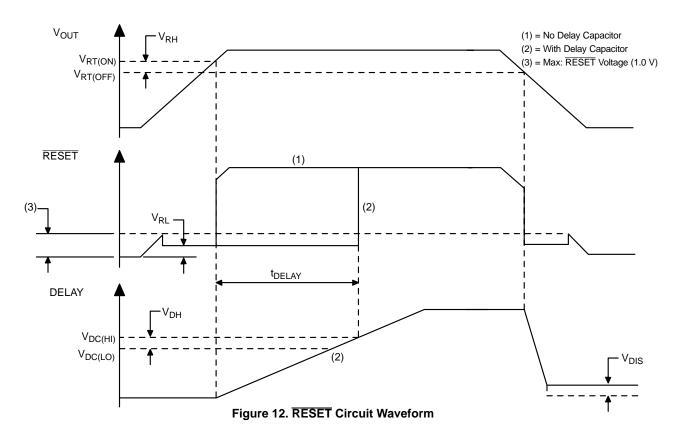


Figure 10. Ripple Rejection

Figure 11. Output Capacitor ESR



CIRCUIT DESCRIPTION

The CS8129 RESET function has hysteresis on both the reset and delay comparators, a latching Delay capacitor discharge circuit, and operates down to 1.0 V.

The RESET circuit output is an open collector type with ON and OFF parameters as specified. The RESET output NPN transistor is controlled by the two circuits described (see Block Diagram on page 2).

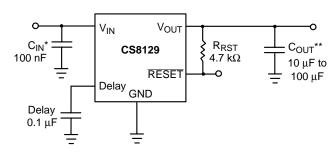
Low Voltage Inhibit Circuit

This circuit monitors output voltage, and when output voltage is below the specified minimum causes the \overline{RESET} output transistor to be in the ON (saturation) state. When the output voltage is above the specified level, this circuit permits the \overline{RESET} output transistor to go into the OFF state if allowed by the \overline{RESET} Delay circuit.

Reset Delay Circuit

This circuit provides a programmable (by external capacitor) delay on the \overline{RESET} output lead. The Delay lead provides source current to the external delay capacitor only when the "Low Voltage Inhibit" circuit indicates that output voltage is above $V_{RT(ON)}$. Otherwise, the Delay lead sinks current to ground (used to discharge the delay capacitor). The discharge current is latched ON when the output voltage is below $V_{RT(OFF)}$. The Delay capacitor is fully discharged anytime the output voltage falls out of regulation, even for a short period of time. This feature ensures that a controlled \overline{RESET} pulse is generated following detection of an error

condition. The circuit allows the \overline{RESET} output transistor to go to the OFF (open) state only when the voltage on the Delay lead is higher than $V_{DC(HI)}$.



*C_{IN} is required if regulator is far from the power source filter.

Figure 13. Test & Application Circuit

The Delay time for the \overline{RESET} function is calculated from the formula:

$$\mbox{Delay time} = \frac{\mbox{CDelay} \times \mbox{VDelay Threshold}}{\mbox{ICharge}}$$

Delay time =
$$C_{Delay(\mu F)} \times 3.2 \times 10^5$$

If $C_{Delay} = 0.1 \,\mu\text{F}$, Delay time (ms) = 32 ms $\pm 50\%$: i.e. 16 ms to 48 ms. The tolerance of the capacitor must be taken into account to calculate the total variation in the delay time.

^{**}COLIT is required for stability.

APPLICATION NOTES

STABILITY CONSIDERATIONS

The output or compensation capacitor helps determine three main characteristics of a linear regulator: start—up delay, load transient response and loop stability.

The capacitor value and type should be based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures (-25°C to -40°C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturers data sheet usually provides this information.

The value for the output capacitor C_{OUT} shown in Figure 13 should work for most applications, however it is not necessarily the optimized solution.

To determine an acceptable value for C_{OUT} for a particular application, start with a tantalum capacitor of the recommended value and work towards a less expensive alternative part.

Step 1: Place the completed circuit with a tantalum capacitor of the recommended value in an environmental chamber at the lowest specified operating temperature and monitor the outputs with an oscilloscope. A decade box connected in series with the capacitor will simulate the higher ESR of an aluminum capacitor. Leave the decade box outside the chamber, the small resistance added by the longer leads is negligible.

Step 2: With the input voltage at its maximum value, increase the load current slowly from zero to full load while observing the output for any oscillations. If no oscillations are observed, the capacitor is large enough to ensure a stable design under steady state conditions.

Step 3: Increase the ESR of the capacitor from zero using the decade box and vary the load current until oscillations appear. Record the values of load current and ESR that cause the greatest oscillation. This represents the worst case load conditions for the regulator at low temperature.

Step 4: Maintain the worst case load conditions set in step 3 and vary the input voltage until the oscillations increase. This point represents the worst case input voltage conditions.

Step 5: If the capacitor is adequate, repeat steps 3 and 4 with the next smaller valued capacitor. A smaller capacitor will usually cost less and occupy less board space. If the output oscillates within the range of expected operating conditions, repeat steps 3 and 4 with the next larger standard capacitor value.

Step 6: Test the load transient response by switching in various loads at several frequencies to simulate its real working environment. Vary the ESR to reduce ringing.

Step 7: Raise the temperature to the highest specified operating temperature. Vary the load current as instructed in step 5 to test for any oscillations.

Once the minimum capacitor value with the maximum ESR is found, a safety factor should be added to allow for the tolerance of the capacitor and any variations in regulator performance. Most good quality aluminum electrolytic capacitors have a tolerance of \pm 20% so the minimum value found should be increased by at least 50% to allow for this tolerance plus the variation which will occur at low temperatures. The ESR of the capacitor should be less than 50% of the maximum allowable ESR found in step 3 above.

CALCULATING POWER DISSIPATION IN A SINGLE OUTPUT LINEAR REGULATOR

The maximum power dissipation for a single output regulator (Figure 14) is:

$$PD(max) = \{VIN(max) - VOUT(min)\}IOUT(max) + VIN(max)IQ$$
 (1)

where:

V_{IN(max)} is the maximum input voltage,

V_{OUT(min)} is the minimum output voltage,

 $I_{OUT(max)}$ is the maximum output current for the application, and

 I_Q is the quiescent current the regulator consumes at $I_{OUT(max)}. \label{eq:IQ}$

Once the value of $P_{D(max)}$ is known, the maximum permissible value of $R_{\Theta JA}$ can be calculated:

$$R_{\Theta JA} = \frac{150^{\circ}C - T_{A}}{P_{D}}$$
 (2)

The value of $R_{\Theta JA}$ can then be compared with those in the package section of the data sheet. Those packages with $R_{\Theta JA}$'s less than the calculated value in equation 2 will keep the die temperature below 150°C.

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required.

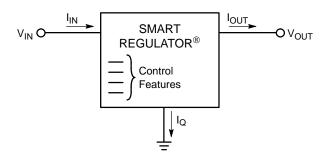


Figure 14. Single Output Regulator With Key Performance Parameters Labeled

CS8129

HEAT SINKS

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\Theta JA}$.

$$R_{\Theta}JA = R_{\Theta}JC + R_{\Theta}CS + R_{\Theta}SA$$
 (3)

where:

 $R_{\Theta JC}$ = the junction-to-case thermal resistance,

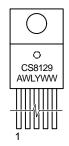
 $R_{\Theta CS}$ = the case–to–heatsink thermal resistance, and

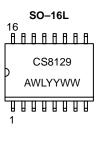
 $R_{\Theta SA}$ = the heatsink-to-ambient thermal resistance.

 $R_{\Theta JC}$ appears in the package section of the data sheet. Like $R_{\Theta JA},$ it too is a function of package type. $R_{\Theta CS}$ and $R_{\Theta SA}$ are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heat sink manufacturers.

MARKING DIAGRAMS







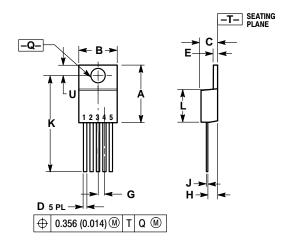
A = Assembly Location

WL, L = Wafer Lot YY, Y = Year

WW, W = Work Week

PACKAGE DIMENSIONS

TO-220 **FIVE LEAD** T SUFFIX CASE 314D-04 ISSUE E



NOTES:

- IOTES:

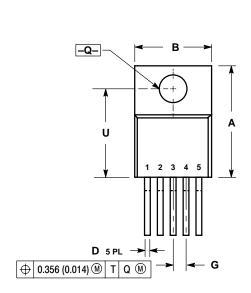
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

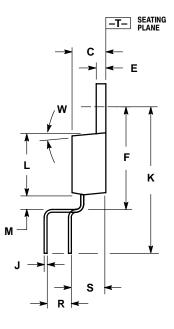
 3. DIMENSION DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.572	0.613	14.529	15.570
В	0.390	0.415	9.906	10.541
С	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067	0.067 BSC		BSC
Н	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	0.990	1.045	25.146	26.543
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972

TO-220 **FIVE LEAD TVA SUFFIX** CASE 314K-01 **ISSUE O**







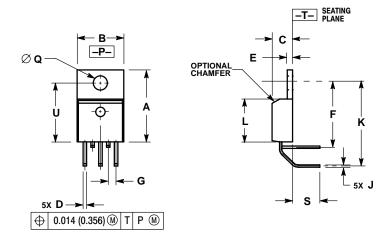
NOTES:

- TIES:

 1. DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE
 INTERCONNECT BAR (DAMBAR) PROTRUSION.
 DIMENSION D INCLUDING PROTRUSION SHALL
 NOT EXCEED 10.92 (0.043) MAXIMUM.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.560	0.590	14.22	14.99	
В	0.385	0.415	9.78	10.54	
С	0.160	0.190	4.06	4.83	
D	0.027	0.037	0.69	0.94	
Е	0.045	0.055	1.14	1.40	
F	0.530	0.545	13.46	13.84	
G	0.067	BSC	1.70 BSC		
J	0.014	0.022	0.36	0.56	
K	0.785	0.800	19.94	20.32	
L	0.321	0.337	8.15	8.56	
M	0.063	0.078	1.60	1.98	
Q	0.146	0.156	3.71	3.96	
R	0.271	0.321	6.88	8.15	
S	0.146	0.196	3.71	4.98	
U	0.460	0.475	11.68	12.07	
W	5°		5	0	

TO-220 **FIVE LEAD THA SUFFIX** CASE 314A-03 ISSUE E

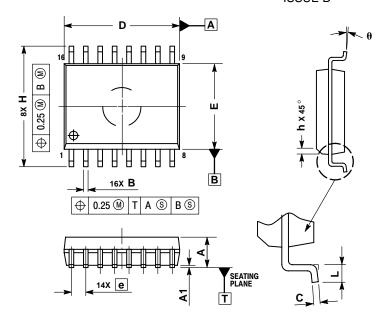


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANGING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.572	0.613	14.529	15.570
В	0.390	0.415	9.906	10.541
С	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
Е	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067	0.067 BSC		BSC
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

SO-16L **DW SUFFIX** CASE 751G-03 **ISSUE B**



NOTES:

- NOTES:

 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE R DIMENSION AT MAXIMUM MATERIAL OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
В	0.35	0.49	
С	0.23	0.32	
D	10.15	10.45	
E	7.40	7.60	
е	1.27	BSC	
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
θ	0 °	7°	

PACKAGE THERMAL DATA

Parameter		TO-220 FIVE LEAD	SO-16L	Unit
$R_{\Theta JC}$	Typical	2.1	23	°C/W
$R_{\Theta JA}$	Typical	50	105	°C/W

Notes

SMART REGULATOR is a registered trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

Fax Response Line: 303-675-2167 or 800-344-3810 Toll Free USA/Canada

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor - European Support

German Phone: (+1) 303–308–7140 (Mon–Fri 2:30pm to 7:00pm CET)
Email: ONlit–german@hibbertco.com

French Phone: (+1) 303–308–7141 (Mon–Fri 2:00pm to 7:00pm CET)

Email: ONlit-french@hibbertco.com

English Phone: (+1) 303–308–7142 (Mon–Fri 12:00pm to 5:00pm GMT)

Email: ONlit@hibbertco.com

EUROPEAN TOLL-FREE ACCESS*: 00-800-4422-3781

*Available from Germany, France, Italy, UK, Ireland

CENTRAL/SOUTH AMERICA:

Spanish Phone: 303-308-7143 (Mon-Fri 8:00am to 5:00pm MST)

Email: ONlit-spanish@hibbertco.com

Toll-Free from Mexico: Dial 01-800-288-2872 for Access -

then Dial 866-297-9322

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 1–303–675–2121 (Tue–Fri 9:00am to 1:00pm, Hong Kong Time)

Toll Free from Hong Kong & Singapore:

001-800-4422-3781 Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 **Email**: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.